

06-04-01

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**PATENT APPLICATION TRANSMITTAL LETTER**  
(Large Entity)

Docket No.  
50544.00004 (NVLS 379)

TO THE ASSISTANT COMMISSIONER FOR PATENTS

Transmitted herewith for filing under 35 U.S.C. 111 and 37 C.F.R. 1.53 is the patent application of:

**Craig L. Stevens and Karl B. Levy**

For: **ARCHITECTURE FOR HIGH THROUGHPUT SEMICONDUCTOR PROCESSING APPLICATIONS**

JC997 U.S. PTO  
09/872796  
06/01/01

Enclosed are:

- ☒ Certificate of Mailing with Express Mail Mailing Label No. **EL701364350US**
- ☒ **Informal (15)** sheets of drawings.
- ☐ A certified copy of a \_\_\_\_\_ application.
- ☒ Declaration ☐ Signed. ☒ Unsigned.
- ☒ Power of Attorney
- ☒ Information Disclosure Statement/Form 1449/Cited References(21)
- ☐ Preliminary Amendment
- ☒ Other: **Gen. Authorization/Req.Pet.f/Ext. of Time; Nonpublication Req.; Patent Application (32 pages)**

**CLAIMS AS FILED**

For	#Filed	#Allowed	#Extra	Rate	Fee
<b>Total Claims</b>	24	- 20 =	4	x \$18.00	\$72.00
<b>Indep. Claims</b>	4	- 3 =	1	x \$80.00	\$80.00
<b>Multiple Dependent Claims (check if applicable)</b> <input type="checkbox"/>					\$0.00
<b>BASIC FEE</b>					\$710.00
<b>TOTAL FILING FEE</b>					\$862.00

- ☐ A check in the amount of \_\_\_\_\_ to cover the filing fee is enclosed.
- ☒ The Commissioner is hereby authorized to charge and credit Deposit Account No. **05-0150** as described below. A duplicate copy of this sheet is enclosed.
- ☒ Charge the amount of **\$862.00** as filing fee.
- ☒ Credit any overpayment.
- ☒ Charge any additional filing fees required under 37 C.F.R. 1.16 and 1.17.
- ☐ Charge the issue fee set in 37 C.F.R. 1.18 at the mailing of the Notice of Allowance, pursuant to 37 C.F.R. 1.311(b).

Dated: **June 1, 2001**

*Patrick D. Benedicto*

Signature

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cc:

**NONPUBLICATION REQUEST  
UNDER  
35 U.S.C. 122(b)(2)(B)(i)**

First Named Inventor	Craig L. Stevens, et. al.
Title	Architecture for High Throughput Semiconductor Processing Applications
Atty Docket Number	50544.00004 (NVLIS 379)

I hereby certify that the invention disclosed in the attached application **has not and will not** be the subject of an application filed in another country, or under a multilateral agreement, that requires publication at eighteen months after filing.

I hereby request that the attached application not be published under 35 U.S.C. 122(b).

June 1, 2001

Date

*Patrick D. Benedicto*

Signature

Patrick D. Benedicto, Reg. No. 40,909

Typed or printed name

This request must be signed in compliance with 37 CFR 1.33(b) and submitted with the application **upon filing**.

Applicant may rescind this nonpublication request at any time. If applicant rescinds a request that an application not be published under 35 U.S.C. 122(b), the application will be scheduled for publication at eighteen months from the earliest claimed filing date for which a benefit is claimed.

If applicant subsequently files an application directed to the invention disclosed in the attached application in another country, or under a multilateral international agreement, that requires publication of applications eighteen months after filing, the applicant **must** notify the United States Patent and Trademark Office of such filing within forty-five (45) days after the date of the filing of such foreign or international application. **Failure to do so will result in abandonment of this application (35 U.S.C. 122(b)(2)(B)(iii)).**